

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSZ0902NS	**Issued**	23. June 2021
MA#	MA005432940		
Package	PG-TSDSON-8-36	**Weight***	35.43 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.419	1.18	1.18	11820	11820
leadframe	inorganic material	phosphorus	7723-14-0	0.004	0.01		103	
	non noble metal	zinc	7440-66-6	0.015	0.04		414	
	non noble metal	iron	7439-89-6	0.293	0.83		8275	
	non noble metal	copper	7440-50-8	11.903	33.60	34.48	336002	344794
wire	noble metal	gold	7440-57-5	0.030	0.08	0.08	837	837
encapsulation	organic material	carbon black	1333-86-4	0.035	0.10		989	
	plastics	epoxy resin	-	1.612	4.55		45507	
	inorganic material	silicondioxide	60676-86-0	15.876	44.82	49.47	448147	494643
leadfinish	non noble metal	tin	7440-31-5	0.420	1.19	1.19	11868	11868
plating	noble metal	silver	7440-22-4	0.003	0.01	0.01	89	89
solder	noble metal	silver	7440-22-4	0.016	0.04		439	
	non noble metal	tin	7440-31-5	0.031	0.09		879	
	non noble metal	lead	7439-92-1	0.576	1.63	1.76	16253	17571
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001			36	
	non noble metal	zinc	7440-66-6	0.005	0.01		142	
	non noble metal	iron	7439-89-6	0.101	0.28		2841	
	non noble metal	copper	7440-50-8	4.087	11.54	11.83	115359	118378
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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